

ABSTRACT OF THE DISCLOSURE

An apparatus is provided for packaging a laminated capacitor made to have a low ESL value and is used for a decoupling capacitor to be connected to a power supply circuit for a MPU chip providing a MPU. The laminated capacitor is accommodated within a cavity provided on a wiring board. The capacitor includes a plurality of first external terminal electrodes connected to first internal electrodes via a plurality of first feedthrough conductors and a plurality of second external terminal electrodes connected to second internal electrodes via a plurality of second feedthrough conductors. The first external terminal electrodes provided on a first major surface of a capacitor body are connected to via-hole conductors at the hot side for the power source within a substrate, and the second external terminal electrodes provided on first and second major surfaces are connected to grounding via-hole conductors and a mother board within the substrate.